

Title (en)
SUBSTRATE TREATING APPARATUS

Title (de)
VORRICHTUNG ZUR BEHANDLUNG VON SUBSTRATEN

Title (fr)
APPAREIL DE TRAITEMENT DE SUBSTRAT

Publication
EP 4345867 A1 20240403 (EN)

Application
EP 23198871 A 20230921

Priority
JP 2022152835 A 20220926

Abstract (en)
Disclosed is a substrate treating apparatus provided with a treating block. The treating block includes a wet transportation region adjoining a batch treatment region and a single-wafer transportation region. The wet transportation region contains a second posture turning mechanism provided on an extension line of a line of six batch process tanks and configured to turn a posture of substrates, on which immersion treatment is performed, from vertical to horizontal, a belt conveyor mechanism configured to receive the substrates in a horizontal posture one by one from the second posture turning mechanism and transport the substrates to the single-wafer transportation region, and a liquid supplying unit configured to supply a liquid to wet the substrates, transported by the belt conveyor mechanism, with the liquid.

IPC 8 full level
H01L 21/677 (2006.01); **H01L 21/67** (2006.01)

CPC (source: EP KR US)
H01L 21/67034 (2013.01 - KR); **H01L 21/67051** (2013.01 - EP KR); **H01L 21/67057** (2013.01 - KR US); **H01L 21/67086** (2013.01 - KR); **H01L 21/6715** (2013.01 - KR); **H01L 21/67173** (2013.01 - KR); **H01L 21/67718** (2013.01 - EP KR US); **H01L 21/67736** (2013.01 - US); **H01L 21/67742** (2013.01 - KR); **H01L 21/67745** (2013.01 - KR); **H01L 21/67748** (2013.01 - KR); **H01L 21/67754** (2013.01 - KR); **H01L 21/67757** (2013.01 - KR); **H01L 21/6776** (2013.01 - KR); **H01L 21/67766** (2013.01 - KR); **H01L 21/67778** (2013.01 - EP); **H01L 21/67781** (2013.01 - EP KR US); **H01L 21/67057** (2013.01 - EP); **H01L 21/67086** (2013.01 - EP); **H01L 21/67757** (2013.01 - EP); **H01L 21/6776** (2013.01 - EP)

Citation (applicant)
• JP 2016502275 A 20140313
• JP 2021064652 A 20210422 - TOKYO ELECTRON LTD
• JP H036581 U 19910122

Citation (search report)
• [YA] JP 2021064652 A 20210422 - TOKYO ELECTRON LTD
• [YA] JP 2018056338 A 20180405 - SCREEN HOLDINGS CO LTD
• [YA] US 2021082720 A1 20210318 - KIKUMOTO NORIYUKI [JP], et al
• [YA] US 2015332940 A1 20151119 - WANG HUI [CN], et al
• [A] KR 20060002266 A 20060109 - SAMSUNG ELECTRONICS CO LTD [KR]
• [A] DE 102007061410 A1 20090618 - SCHMID GMBH & CO GEB [DE]
• [A] JP S57154854 A 19820924 - HITACHI LTD, et al

Designated contracting state (EPC)
AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC ME MK MT NL NO PL PT RO RS SE SI SK SM TR

Designated extension state (EPC)
BA

Designated validation state (EPC)
KH MA MD TN

DOCDB simple family (publication)
EP 4345867 A1 20240403; CN 117766442 A 20240326; JP 2024047292 A 20240405; KR 20240043686 A 20240403; US 2024105486 A1 20240328

DOCDB simple family (application)
EP 23198871 A 20230921; CN 202311200617 A 20230918; JP 2022152835 A 20220926; KR 20230122461 A 20230914; US 202318472922 A 20230922